



SOT487-1

plastic, thin shrink small outline package; 32 leads; 0.65 mm pitch; 11 mm x 6.1 mm x 0.9 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP32
Package type industry code	TSSOP32
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	18-2-2003
Manufacturer package code	SOT487

Table 1. Package summary

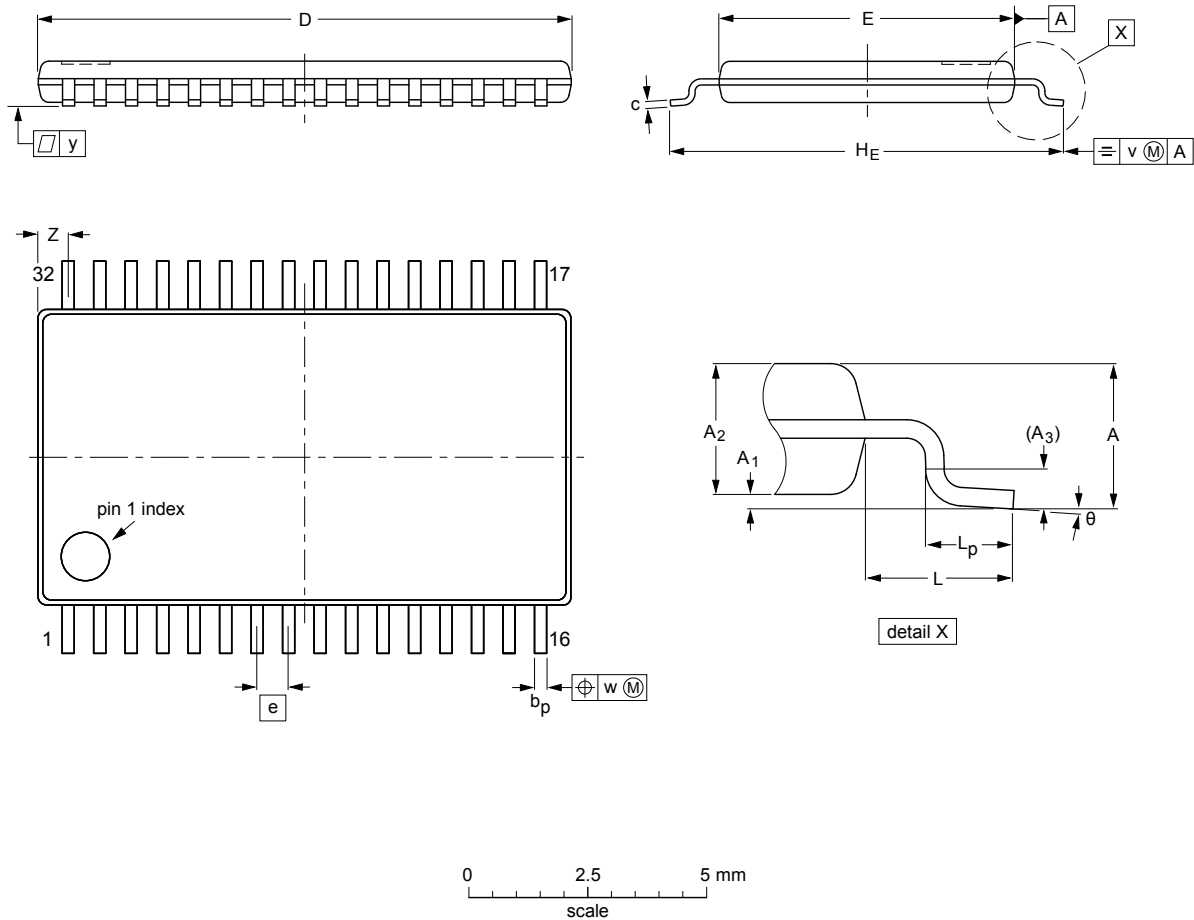
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.9	-	11	11.1	mm
E	package width	6	-	6.1	6.2	mm
A	seated height	-	-	1.1	1.1	mm
A ₂	package height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	32	-	

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2. Package outline

TSSOP32: plastic thin shrink small outline package; 32 leads; body width 6.1 mm; lead pitch 0.65 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	v	w	y	Z	θ
mm	1.1	0.15 0.05	0.95 0.85	0.25	0.30 0.19	0.20 0.09	11.1 10.9	6.2 6.0	0.65	8.3 7.9	1	0.75 0.50	0.2	0.1	0.1	0.78 0.48	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT487-1		MO-153				99-12-27 03-02-18

Fig. 1. Package outline TSSOP32 (SOT487-1)

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3. Soldering

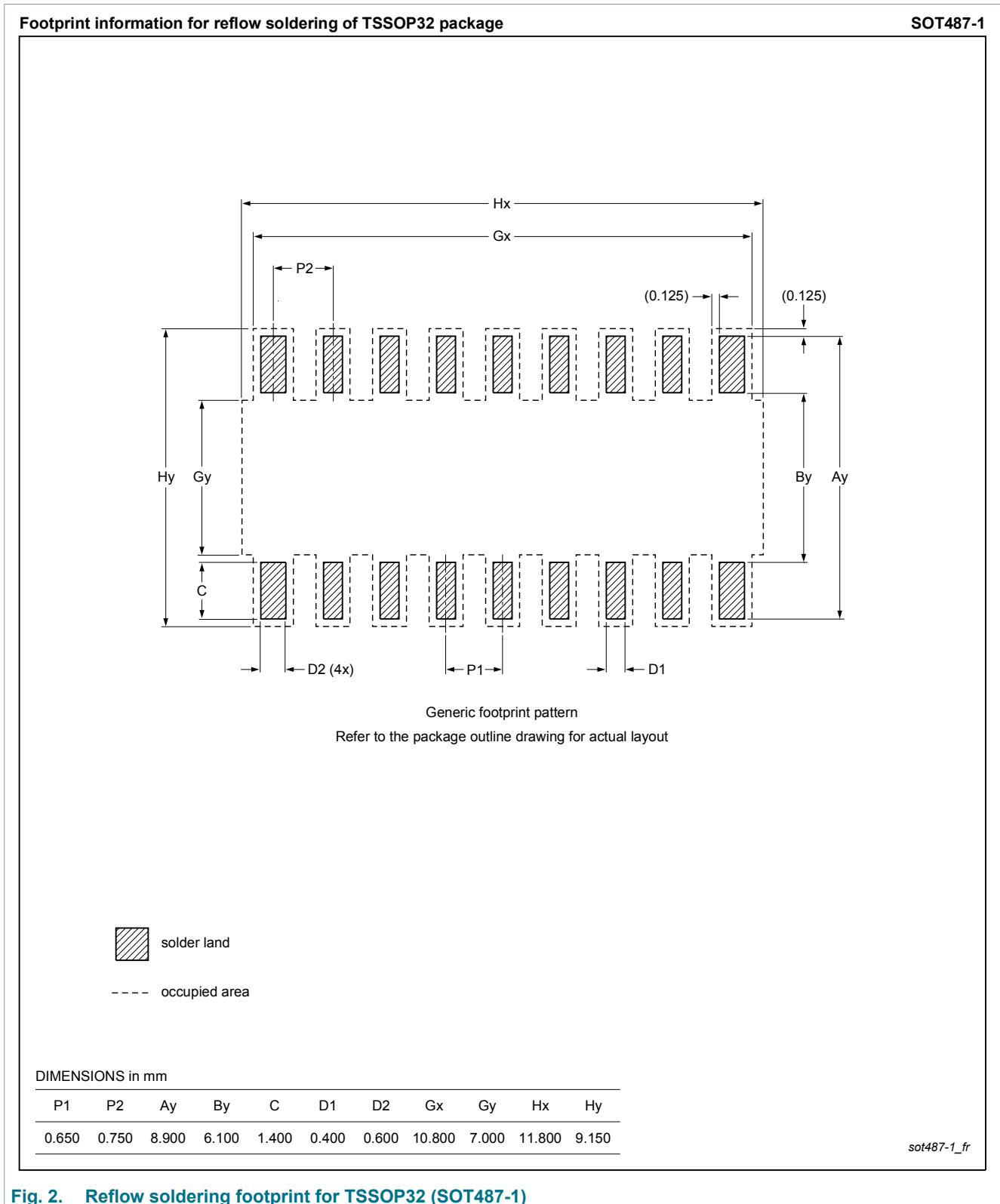


Fig. 2. Reflow soldering footprint for TSSOP32 (SOT487-1)

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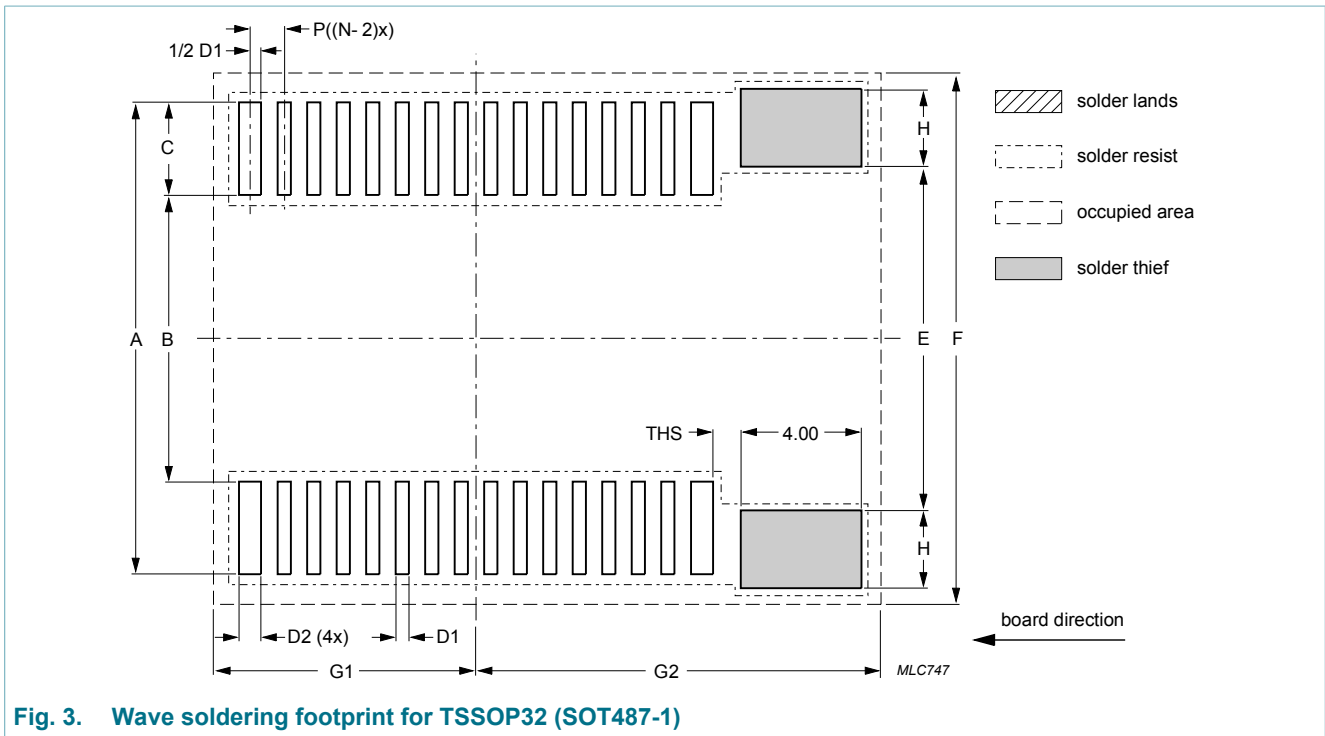


Fig. 3. Wave soldering footprint for TSSOP32 (SOT487-1)

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4. Legal information

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